# **ECE 3040 Microelectronic Circuits**

Exam 1

February 19, 2007

Dr. W. Alan Doolittle

Print your name clearly and largely:	Solutions	232 min	utes
Instructions: Read all the problems carefully and the to use 1 new sheet of notes (1 page from total points. Observe the point value of SHOW ALL WORK AND CIRCLE YUNITS INDICATED. Write legibly, answer. Do all work on the paper proto an answer. Report any and all ethics	ont and back) as well as of each problem and allow YOUR FINAL ANSWE If I cannot read it, it will wided. Turn in all scrate	gin working. You a a calculator. There cate your time acco R WITH THE PRO I be considered a w h paper, even if it d	are allowed are 100 ordingly. OPER vrong
Sign your name on <b>ONE</b> of the two fo	ollowing cases:		
I DID NOT observe any ethical violat	ions during this evam:		
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I observed an ethical violation during	this exam:		

# First 33% Multiple Choice and True/False (Circle the letter of the most correct <u>answer or answers</u>)

1.)	(3-points) True or False: MBE is an epitaxy technique performed at very high pressures above
2.)	atmospheric pressure.  (3-points) True or False: If a semiconductor has a large inter-atomic spacing it will likely have a
3.)	large bandgap.  (3-points) True or False: The density of states describes the probability that a particular state at
4.)	energy, E, is occupied. (3-points) True or False: An indirect bandgap material (such as Germanium and Silicon) results in a longer minority carrier lifetime than a direct bandgap material.
5.)	(3-points) True or False: For direct bandgap materials there is no difference in momentum between electrons and holes.
6.)	(3-points) True or False: The probability of occupying a state located at the fermi-energy is always 1.
7.)	(3-points) True or False: Auger recombination occurs when an electron is captured by a defect inside the bandgap then drops to the valence band killing off a hole.
	cet the <u>best</u> answer or answers for 6-10:  (4-points) The law of mass action  a.) describes the balance between electrons and holes.  b.) indicates that an increase of electron concentration beyond the intrinsic concentration results in a decrease in the hole concentration  c.) indicates that at constant temperature the product of electrons and holes is constant d.) only applies to non-degenerate doping conditions.  e.) Who knows!!!!
	<ul> <li>(4-points) The electrons in the conduction band?</li> <li>a.) Are immobile</li> <li>b.) Are most often found exactly at the lowest energy, at the conduction band edge</li> <li>c.) Can be heavier than the free space (vacuum) electron mass</li> <li>d.) Can be lighter than the free space (vacuum) electron mass</li> <li>e.) Are always lighter than the free space (vacuum) electron mass due to their interaction with the atoms in the crystal</li> </ul>
10.)	(4-points) The following energy band diagram indicates the material is:  a.) Degenerate and n-type  b.) In equilibrium  c.) Non-degenerate n-type  d.) Degenerate and p-type  e.) In low level injection  f.) Non-degenerate p-type  g.) In steady state
	$E_{v} + 3kT$ $E_{f} = F_{P}$

## 6 minutes

Second 57% Short Answer ("Plug and Chug"):

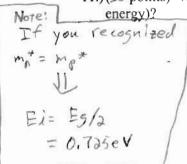
For the following problems (11-12) use the following material parameters:

 $n_i = 1e6 \text{ cm}^{-3}$ 

 $N_A=1e18~cm^{-3}~acceptors$   $m_p^*=0.5m_o$   $m_n^*=0.5m_o$ Electron mobility,  $\mu_n=900~cm^2/Vsec$  Hole mobility ,  $\mu_p=10~cm^2/Vsec$  $E_G = 1.45 \text{ eV}$ 

Temperature= 27 degrees C

11.) (16-points) Where is the intrinsic energy (relative to the valence band which is referenced to zero



$$E_{i} = \frac{E_{c} + E_{v}}{2} + \frac{3bT}{4} l_{n} \left( \frac{m^{*}e}{m^{*}s} \right)$$

$$\frac{1.45}{2} + 0.75 \left( 0.0259 \right) l_{n} \left( \frac{0.5}{0.5} \right)$$

$$E_{i} = 0.725 \text{ eV}$$

12.) (#\*points) What is the resistivity of the semiconductor?

#### Third 25%



13.)(25-points total) Sometimes semiconductors are used for radiation detectors. A 100 um x 100 um x 100 um cube of intrinsic silicon-carbide (SiC) material with bandgap  $E_g=3.0$  eV is to be used as an x-ray detector. The semiconductor has an intrinsic concentration, n<sub>i</sub>=1e-9 cm<sup>-3</sup>, an electron mobility of 500 cm<sup>2</sup>/V-sec and a hole mobility of 50 cm<sup>2</sup>/V-sec. The cube is biased on two opposing sides with 3,000 volts. Each x-ray photon has an energy of 30,000 eV meaning that each x-ray photon has enough energy to produce **many** electron hole pairs. If a single x-ray photon strikes the semiconductor...

(3 points) What type (diffusion, drift, electron dominated, hole dominated, etc...) of current results?

&-field > drift
Intrinsic => both electrons + holes are important Inports and Jepoits

(7 points) Draw the 1 dimensional energy band diagram in the direction of the electric field indicating the actual slope of the bands (numeric answer).

& = 1 dEc = 3000 V/cm = 300,000 V/cm

 $\frac{dE_c}{dx} = q \mathcal{E} = (1.6e-19 \text{ Coulombs}) (3ag,000 \text{ V/cm}) (\frac{1eV}{1.6e-19J})$  = 3ag,000 eV/cm

(15 – points) Assuming all photogenerated electrons and holes are collected instantaneously as current, what is the current (not current density) that results? Hint: consider how much energy it takes to generate an electron-hole pair verses how much energy the x-ray photon has.

cross area  $n = p = 1e-9 + \frac{30,000 eV/photon}{3,0 eV/ehp} (1photon) \frac{1}{(0.01)^3}$   $N = p = 10^{10} rm^{-3}$ 

$$I = A J_{oriff} = q (pup + n un) \in A$$

$$= (1.6e-19) (500 + 50) le 10 (300,000) (0.01)^{2}$$

$$I = 26.4 \text{ uA}$$

Pulling all the concepts together for a useful purpose:

### 14.) (30-points)

Surfaces of a crystalline semiconductor represent regions where recombination is higher than in the bulk (inside the semiconductor) and thus, lower the excess minority carrier concentrations near the crystal surfaces. George Washington (America's 1<sup>st</sup> president) lit a candle that shines on a 50 µm thick p-type GaAs semiconductor held at room temperature (27 degrees C). The light uniformly generates 10<sup>22</sup> additional holes per cm³ per second throughout the semiconductor but the surface recombination is such that there are no excess carriers at both the surfaces. Determine the minority carrier current density at all positions in the semiconductor. Assume a minority carrier lifetime of 10 nanoseconds (1e-8 seconds), and minority carrier diffusion coefficient at room temperature of 4.0 cm²/sec.

Given:  $0 = D_n \frac{d^2 \Delta n_p}{dx^2} - \frac{\Delta n_p}{\tau_n}$  General Solution is:  $\Delta n_p(x) = Ae^{-\frac{x}{L_n}} + Be^{+\frac{x}{L_n}}$ Given:  $0 = D_n \frac{d^2 \Delta n_p}{dx^2} - \frac{\Delta n_p}{\tau_n} + G_L$  General Solution is:  $\Delta n_p(x) = Ae^{-x/L_n} + Be^{+x/L_n} + G_L \tau_n$ Given:  $0 = D_n \frac{d^2 \Delta n_p}{d^2 \Delta n_p}$ General Solution is:  $\Delta n_n(x) = A + Bx$ Given:  $0 = D_n \frac{d^2 \Delta n_p}{dx^2} + G_L$ General Solution is:  $\Delta n_n(x) = Ax^2 + Bx + C$ Given:  $0 = D_n \frac{d^2 \Delta n_p}{dx^2} + G_{LO} f(x)$  General Solution is:  $\Delta n_p(x) = \left| -\frac{G_{LO}}{D_n} \iint f(x) dx \right| + Bx + C$ Given:  $\frac{d\Delta n_p}{dt} = -\frac{\Delta n_p}{\tau}$ General Solution is:  $\Delta n_p(t) = \Delta n_p(t=0)e^{-t/\tau_n}$ Given:  $0 = -\frac{\Delta n_p}{\tau_L} + G_L$  $= \sqrt{0_n \, \tau_n}$   $= \sqrt{(4) \, (1e-8)} \qquad \Delta_{np}(x=0) \qquad \Delta_{np}(x=0) = 0$   $= 2 \times 10^{-4} \, cm = 2 \, am$ Boundary Condition

1) Dnp (x=0) = A + B + 6, 2n = 0 = A + B + 1014

2) Ang (x=50 Am) = Ap-50/2 + Be+50/2 + 1e14=0

A = (1e14-B) U  $(1e14-B)e^{-25} + Be^{+25} + 1e14 = 0$ 

Extra work can be done here, but clearly indicate which problem you are solving.

$$B = -\frac{1614}{e^{25}} = -1,388.8 \text{ cm}^{-3}$$

$$A = -1614 - B$$

$$A = -1614 - B$$

$$A = -1614 e^{-x/2nm} - 1388.8 e^{+x/3nm} + 1614 \text{ cm}^{-3}$$

$$D = -1614 e^{-x/2nm} - 1388.8 e^{+x/3nm} + 1614 \text{ cm}^{-3}$$

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$$D = -1614 e^{-x/2nm} - (1388.8) e^{+x/3nm} + 1614 \text{ cm}^{-3}$$

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